

Electronic Acknowledgement Receipt

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International Application Number:	
Confirmation Number:	6093
Title of Invention:	Chip package with die and substrate
First Named Inventor/Applicant Name:	Mou-Shiung Lin
Customer Number:	89518
Filer:	Dennis Alan Duchene/Patricia Balero
Filer Authorized By:	Dennis Alan Duchene
Attorney Docket Number:	085027-0059
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Application Type:	Utility under 35 USC 111(a)

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Submitted with Payment	no
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/ Message Digest	Multi Part /.zip	Pages (if appl.)
1		DolceraInformationDisclosureS tatement-085027-0059.pdf	165549 ece94b3e60c3ff18c1677419b6e10e0e64bf 7c4e	yes	5

	Multipart Description/PDF files in .zip description				
	Document Description		Start	End	
	Transmittal Letter		1	3	
	Information Disclosure Statement (IDS) Filed (SB/08)		4	5	
Warnings:					
Information:					
2		TS-5InformationDisclosureState ment-085027-0059.pdf	159675 669ea5b1b45f909801778d72c50ee2be758 aaa64	yes	4
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4	NPL Documents	1_MISTRY_45nm_logic.pdf	2254221 072127b124142b87d48b36305577e00d7f2 81092	no	4
Warnings:					
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5	NPL Documents	2_EDELSTEIN_Advantages_of_ Copper.pdf	3696109 daa31204b1d9d203a708a79ef619df46550 68f74	no	9
Warnings:					
Information:					

6	NPL Documents	3_THENG_An_automated_tool_deployment_for_ESD.pdf	4517666	no	7
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7	NPL Documents	4_GAO_An_improved_electros tatic_discharge_protection_str ucture.pdf	885848	no	6
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8	NPL Documents	5_YOEH_Copper_Die_Bumps. pdf	717153	no	5
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10	NPL Documents	7_ROESCH_Cycling_Copper_Fli p_Chip_Connects.pdf	1142794	no	8
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Total Files Size (in bytes):			41286616		

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New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.

New International Application Filed with the USPTO as a Receiving Office

If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.